

**ABSTRACT OF THE DISCLOSURE**

A bonding pad structure to avoid probing damage applied to IC or PCB products comprises a first pad and at least one second pad. The first pad is coupled with the second pad. The first pad is used for wire bonding & packaging while the second pad is used for probing in IC function testing. Therefore, it avoids the probing damage of the first pad after the IC function testing and further increases the IC reliability while wire bonding & packaging.

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